GainForce Technology Co.,Ltd

嘉光科技股份有限公司

承認書

APPROVAL SHEET

品	名:	Anten	na						
MODE	EL NAME								
料	號:	AT3216-T2R4PAAT/LF							
PART	NUMBER								
客戶	与名稱:	永氵	¥						
CUS	STOMER	11320Y111	41A1						
供	應 商:	GainFo	orce						
	VENDOR								
使月	用機種:								
	MODEL								
		<u>尹</u> 廣	<u>汶</u> 80-1838						
附	件:								
AC	CESSORIES	規格書	樣品						
		SPECIFICATION	SAMPLE						
		圖樣	檢驗報告						
		DRAWING	TEST REPORT						

認可狀況:

(APPROVED STATUS)



APP.NO.:____

1.	零件基本資料	-P3
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AT3216 Series (Preliminary)

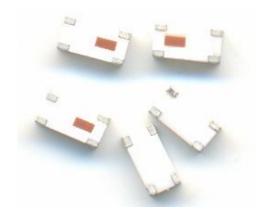
Multilayer Chip Antenna

Features

- ❖ Monolithic SMD with small, low-profile and light-weight type.
- ❖ Wide bandwidth

Applications

- ❖Bluetooth/Wireless LAN/Home RF
- ❖ISM band 2.4GHz applications



Specifications

Part Number	Frequency Range (MHz)	Peak Gain (XZ-total)	Average Gain (XZ-total)	VSWR	Impedance	
AT3216 -T2R4PAA_	2400 ~ 2500	1.5 dBi typ.	-1.0 dBi typ.	3.0 max.	50 Ω	

Q'ty/Reel (pcs) : 3,000pcs Operating Temperature Range : $-40 \sim +85$ °C

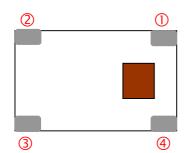
Storage Temperature Range : +5 ~ +35 °C, Humidity 45~75%RH

Storage Period : 12 months max. Power Capacity : 2W max.

Part Number

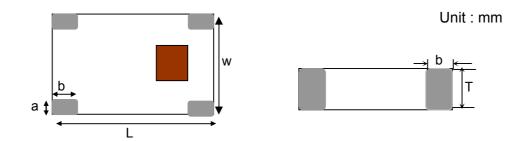
① Туре	AT : Antenna	② Dimensions (L × W)	3.2× 1.6 mm
3 Material Code	Т	Frequency Range	2R4=2400MHz
Specification Code	PAA	6 Packaging	T: Tape & Reel B: Bulk
	=lead-containing /LF=lead-free		

Terminal Configuration



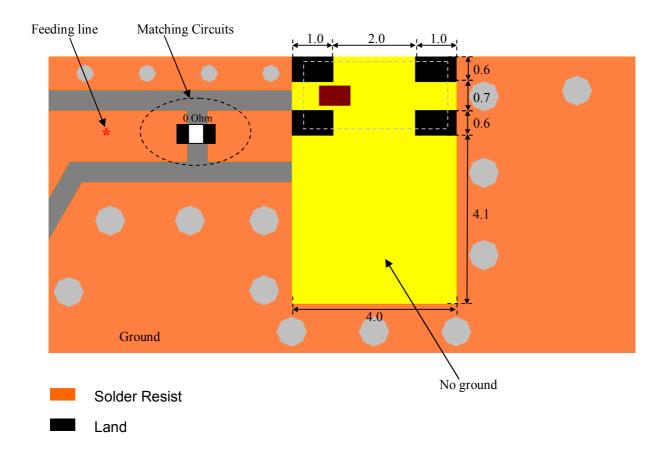
No.	Terminal Name	No.	Terminal Name
1	Feeding Point	2	GND
3	GND	4	GND





Mark	L	W	T	а	b
Dimensions	3.2±0.2	1.6±0.2	1.2±0.2	0.3+0.1 /-0.2	0.5±0.2

❖Without Matching Circuits - Unit in mm

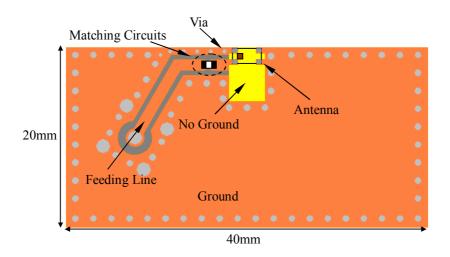


^{*}Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

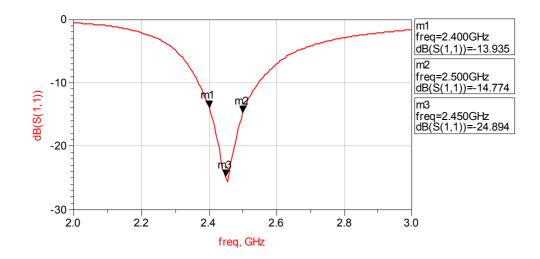


Typical Electrical Characteristics (T=25°C)

❖Test Board

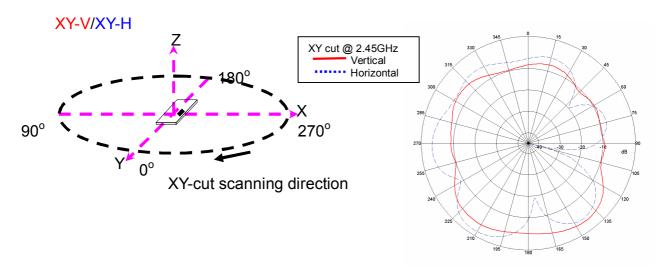


❖Return Loss-without matching circuits

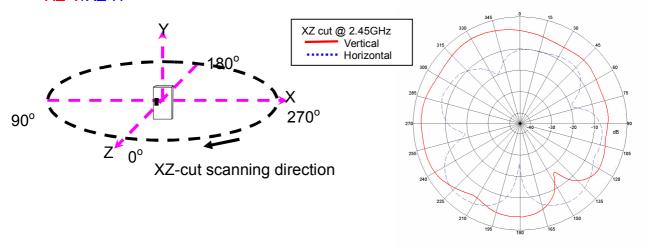




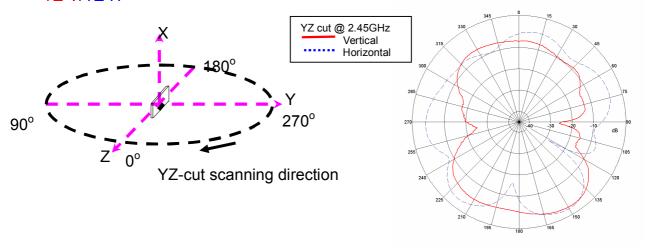
❖Radiation Patterns



XZ-V/XZ-H

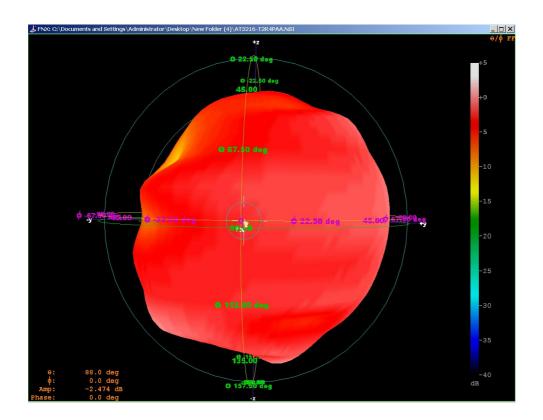


YZ-V/YZ-H





❖ Radiation Patterns - 3D Pattern



Advanced Ceramic X Corp.

16 Tzu Chiang Road, Hsinchu Industrial District Hsinchu Hsien 303, Taiwan TEL:886-3-5987008 FAX:886-3-5987001

E-mail: acx@acxc.com.tw http://www.acxc.com.tw



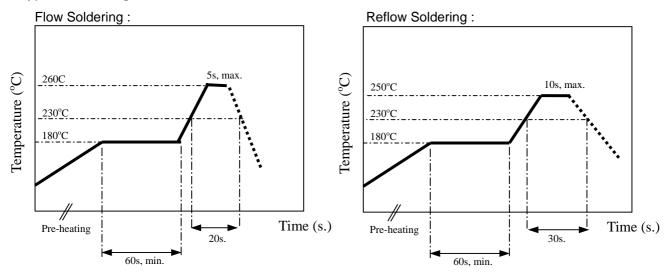
Mechanical & Environmental Characteristics

		Requirements		Procedure
Solderability	1. 2.	No apparent damage More than 75% of the terminal electrode shall be covered with new solder		
Thermal shock (Temperature Cycle)	1. 2.	No apparent damage Fulfill the electrical specification after test	1. 2. 3. 4.	One cycle/ step 1: 85 ± 5 °C for 20sec step 2: -40 ± 3 °C for 20sec Cycle time: 30min No. of cycles: 100 Recovery: 1-2hrs
Heat Resistance	1. 2.	No apparent damage Fulfill the electrical specification after test	1. 2. 3.	Temperature: 85± 2 °C Duration: 24±2hrs Recovery: 1-2hrs
Low Temperature Resistance	1. 2.	No apparent damage Fulfill the electrical specification after test	1. 2. 3.	
Humidity Resistance	1. 2.	No apparent damage Fulfill the electrical specification after test	1. 2. 3. 4.	Humidity: 80% ~ 85% RH Duration: 1000±48hrs
Soldering strength (Push strength)	1.	9.8N minimum	1. 2.	, , ,
Deflection (Bending)	1. 2.	No apparent damage Fulfill the electrical specification	,	Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. Apply a bending force of 2mm deflection Pressure Rod R230 90mm
Drop Shock	1.	No apparent damage	1.	Dropped onto hard wood from height of 50 cm for 3 times; each x,y and z direction except terminal direction



Typical Soldering Profile

❖Typical Soldering Profile for Lead-free Process



The sample must be pre-heated before soldering .The temperature difference between preheating and soldering must be within 150 .

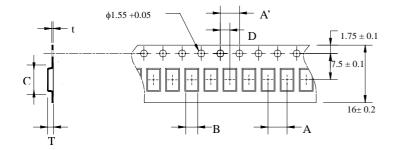
Notes

❖The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.



Taping Specifications

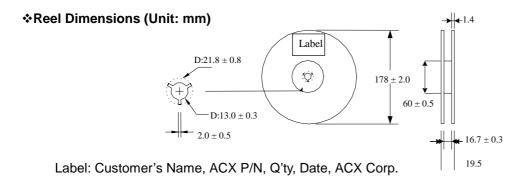
❖Tape Dimensions (Unit: mm)



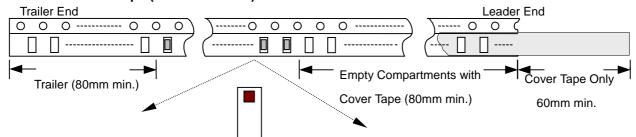
Туре	Α	A'	В	С	D	t	Т
3216	4.0±	4.0±	1.9±	3.5±	2.0±	0.20±	Max.
	0.1	0.1	0.1	0.1	0.1	0.05	1.4
5020	4.0±	4.0±	2.4±	5.5±	2.0±	0.20±	Max.
	0.1	0.1	0.1	0.1	0.1	0.05	1.4
7020	4.0±	4.0±	2.4±	7.3±	2.0±	0.22±	Max.
	0.1	0.1	0.1	0.1	0.1	0.05	1.55
7635	8.0±	4.0±	3.75±	7.85±	2.0±	0.30±	Max.
	0.1	0.1	0.1	0.1	0.1	0.05	1.40
8516	4.0±	4.0±	1.85±	8.70±	2.0±	0.25±	Max.
	0.1	0.1	0.1	0.1	0.1	0.05	1.40
9520	4.0±	4.0±	2.3±	9.7±	2.0±	0.22±	Max.
	0.1	0.1	0.1	0.1	0.1	0.05	1.45
R130	8.0±	4.0±	3.35±	10.35	2.0±	0.25±	Max.
	0.1	0.1	0.1	±0.1	0.1	0.05	1.40

❖Quantity

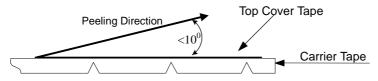
Туре	3216	5020	7020	7635	8516	9520	R130
Quantity	3,000pcs	2,000	1,000 pcs	1,000 pcs	1000pcs	1,000 pcs	1,000 pcs
/per reel	3,000pcs	2,000	1,000 pcs	1,000 μεδ	τουορισ	1,000 pcs	1,000 pcs



❖Leader and Trailer Tape (Plastic material)



❖Peel-off Force



Peel-off force should be in the range of 0.1-0.6~N at a peel-off speed of $300\pm10~mm/min$.

ACX

❖Storage Conditions

- (1) Temperature: 15 ~35 , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment
- (3) Products should be used within six months of receipt.

Notes

❖The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.



Test Report Page: 1 of 5 No.: CE/2012/55830 Date: 2012/06/06

ADVANCED CERAMIC X (ACX) CORPORATION 16 TZU CHIANG ROAD, HSINCHU INDUSTRIAL DISTRICT, HSINCHU HSIEN, TAIWAN 303



The following sample(s) was/were submitted and identified by/on behalf of the client as:

Sample Description : MULTILAYER LTCC-L COMPONENTS (CERAMIC BODY)

Style/Item No. : AD SERIES, AM SERIES, AT SERIES, AW SERIES, BD SERIES, BF SERIES,

BL SERIES, BM SERIES, BW SERIES, CD SERIES, CF SERIES, CP SERIES, DM SERIES, DP SERIES, DS SERIES, ES SERIES, FA SERIES, FB SERIES, FD SERIES, GS SERIES, HI SERIES, HF SERIES, HM SERIES, HS SERIES, LF SERIES, OM SERIES, OS SERIES, PD SERIES, NF SERIES, QS SERIES,

SF SERIES, TS SERIES, LTCC SUBSTRATES, BCM2037

Buyer/Order No. : LOCAL COMPANY OR USA COMPANY

Sample Receiving Date : 2012/05/30

Testing Period : 2012/05/30 TO 2012/06/06

: As specified by client, with reference to RoHS Directive 2011/65/EU Annex II to **Test Requested**

determine Cadmium, Lead, Mercury, Cr(VI), PBBs, PBDEs contents in the

submitted sample.

Test Method With reference to IEC 62321: 2008.

: Please refer to next page(s). Test Result(s)





Test Report Page: 2 of 5 No.: CE/2012/55830 Date: 2012/06/06

ADVANCED CERAMIC X (ACX) CORPORATION 16 TZU CHIANG ROAD, HSINCHU INDUSTRIAL DISTRICT, HSINCHU HSIEN, TAIWAN 303



Test Result(s)

PART NAME No.1 MULTILAYER LTCC-L COMPONENTS (CERAMIC BODY)

Test Item(s)	Unit	Method	MDL	Result
l est item(s)	Offic	Wiethod	IVIDE	No.1
Cadmium (Cd)	mg/kg	With reference to IEC 62321: 2008	2	n.d.
Lead (Pb)	mg/kg	and performed by ICP-AES.	2	12
Mercury (Hg)	mg/kg	and performed by for -ALS.	2	n.d.
Hexavalent Chromium Cr(VI)	mg/kg	With reference to IEC 62321: 2008 and performed by UV-VIS.	2	n.d.
Sum of PBBs	mg/kg		-	n.d.
Monobromobiphenyl	mg/kg	1	5	n.d.
Dibromobiphenyl	mg/kg	1	5	n.d.
Tribromobiphenyl	mg/kg	1	5	n.d.
Tetrabromobiphenyl	mg/kg	1	5	n.d.
Pentabromobiphenyl	mg/kg	1	5	n.d.
Hexabromobiphenyl	mg/kg	1	5	n.d.
Heptabromobiphenyl	mg/kg	1	5	n.d.
Octabromobiphenyl	mg/kg	1	5	n.d.
Nonabromobiphenyl	mg/kg	1	5	n.d.
Decabromobiphenyl	mg/kg	With reference to IEC 62321: 2008	5	n.d.
Sum of PBDEs	mg/kg	and performed by GC/MS.	-	n.d.
Monobromodiphenyl ether	mg/kg		5	n.d.
Dibromodiphenyl ether	mg/kg		5	n.d.
Tribromodiphenyl ether	mg/kg	1	5	n.d.
Tetrabromodiphenyl ether	mg/kg	1	5	n.d.
Pentabromodiphenyl ether	mg/kg	1	5	n.d.
Hexabromodiphenyl ether	mg/kg]	5	n.d.
Heptabromodiphenyl ether	mg/kg]	5	n.d.
Octabromodiphenyl ether	mg/kg	1	5	n.d.
Nonabromodiphenyl ether	mg/kg	1	5	n.d.
Decabromodiphenyl ether	mg/kg]	5	n.d.

1. mg/kg = ppm; 0.1wt% = 1000ppm

2. n.d. = Not Detected

3. MDL = Method Detection Limit

4. " - " = Not Regulated



Test Report

No.: CE/2012/55830 Date: 2012/06/06

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ADVANCED CERAMIC X (ACX) CORPORATION 16 TZU CHIANG ROAD, HSINCHU INDUSTRIAL DISTRICT, HSINCHU HSIEN, TAIWAN 303

- 1) These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr⁶⁺ test method excluded)
- 2) Name of the person who made measurement: Climbgreat Yang
- 3) Name of the person in charge of measurement: Troy Chang Cutting / Preparation Sample Measurement Cr6+ Hg (Note**) Pb · Cd Acid digestion by suitable acid Microwave digestion with Add appropriate amount of depended on different sample HNO₃/HCI/HF digestion reagent material (as below table) Filtration Heat to appropriate temperature to extract Residue Solution Cool, filter digestate Alkali Fusion through filter HCI to dissolve **ICP-AES** Add diphenyl-carbazide for **Digestion Acid** color development Sample Material Steel, copper, aluminum, solder Aqua regia, HNO₃, HCl, HF, H₂O₂ HNO₃/HF measure the absorbance Glass at 540 nm by UV-VIS Gold, platinum, palladium, ceramic Aqua regia Silver HNO_3 **Plastic** H₂SO₄, H₂O₂, HNO₃, HCI Added appropriate reagent to total Others

Note**: (1) For non-metallic material, add alkaline digestion reagent and heat to 90~95 ℃.

(2) For metallic material, add pure water and heat to boiling.

digestion



Test Report

No.: CE/2012/55830 Date: 2012/06/06

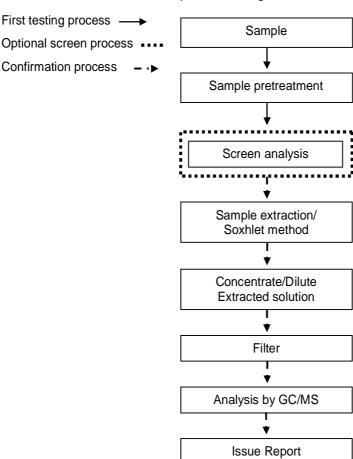
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ADVANCED CERAMIC X (ACX) CORPORATION 16 TZU CHIANG ROAD, HSINCHU INDUSTRIAL DISTRICT, HSINCHU HSIEN, TAIWAN 303



PBB/PBDE analytical FLOW CHART

- Name of the person who made measurement: Roman Wong
- Name of the person in charge of measurement: Troy Chang





Test Report

No.: CE/2012/55830

Date: 2012/06/06

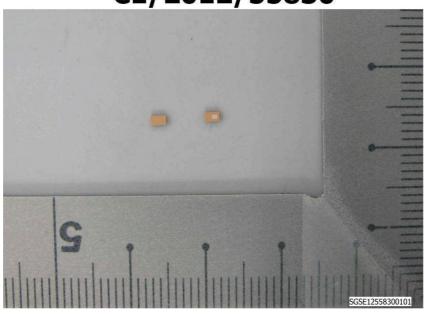
Page: 5 of 5

ADVANCED CERAMIC X (ACX) CORPORATION 16 TZU CHIANG ROAD, HSINCHU INDUSTRIAL DISTRICT, HSINCHU HSIEN, TAIWAN 303



* The tested sample / part is marked by an arrow if it's shown on the photo. *

CE/2012/55830



** End of Report **

Iten	1 永洋料號 (P/N)	永洋品名 (Description)	原廠/製造商型 號 (SUPPLIER PN)	原/製商稱	零件單重	分離之均勻 材質 (Homogene ous Material) Sub-parts	原材料顏色 (塑膠、油 墨及漆料必 填) The color of raw material (Required for plastic, ink and paint)	競層存 在與層材 質説明 If the plating layer exist or not?(Y/ N)/If yes, please describe the material of the plating layer	分 之 均 材 單 (mg)	鉛 (Pb)		#	六價 路(Cr+ 6)		PBDE	PFOS	實驗名稱	分析報告 號碼	食測報告日其		第三公 <mark>證</mark> 單位 PFOS 分析報告 Attached test report	元素/化合物	成份表 元素/化 合物 比重 (%)	款	材質證明
1	11320Y11141A1	CHIP Antenna AT3216- T2R4PAATL F	AT3216- T2R4PAAT/LF	璟德電子	18 18	Ceramic	NA	N	16.22	N.D	N.D	N.D	N.D	N.D	N.D	N.D	SGS	CE/2012/30808 CE/2012/52120	2012/3/8 2012/5/18	CE_2012_30808.pd	CE_2012_52120	Al2O3 SiO2 CaO TiO2 MgO	57.0% 28.2% 8.1% 1.8% 1.0%		
		r				Termination Plating	NA	Y(Ni / Sn)	2.26	N.D	N.D	N.D	N.D	N.D	N.D	N.D		CE/2012/52122 CE/2012/52120	2012/5/18 2012/5/18	CE_2012_52122		Ag Ni Sn	65.1% 11.6% 23.2%		

	**************************************	勿質成份:	元素表		
組成物	材質	材質比重	元 素	元素比重	備註
			A12O3	56.99%	
			SiO2	28.24%	
Ceramic	Powder	87.76%	CaO	8.07%	
Ceramic	Powder	87.70%	TiO2	1.77%	
			MgO	0.98%	
			Ag	3.95%	
			Ag	65.1%	
Termination	Ag paste; plating	12.24%	Ni	11.6%	
	plating		Sn	23.2%	
	1				

物質成份分析表

料	號	組成物名稱	鉛(Pb)	鎘(Cd)	汞(Hg)	六價鉻 (Cr+6)	多溴聯苯 (PBBs)	多溴化二苯 乙醚 (PBDEs)	ROHS檢測報告編號	檢測日期	排除條例
AT3216-T2R	AT3216-T2R4PAAT/LF		N.D	N.D	N.D	N.D	N.D	N.D	CE/2012/30808	2012/3/8	
11320Y1	1141A1	Termination	N.D	N.D	N.D	N.D	N.D	N.D	CE/2012/52122	2012/5/18	

註:1.若物質成份含量超出RoHS所限定之含量,但在RoHS的排除條款中,請供應商在檢測報告及表單中清楚註明是在一條文中所規定,以方便查核。

2.若物質超出RoHS限定值,請附上材質證明,以證明所含之成份是RoHS所允許。

永洋 RoHS 値管制標準

Classification	Restr	icts Substar	ices	AMIT Standard	備註
	Lead (Lead Compounds)	鉛及其 化合物	Pb	800ppm	例外(Exception): 1.鉛使用於電子器材中陶 製零件不受此限。 2.鋼合金:0.35%(3500ppm) 3.鋁合金:0.40%(4000ppm) 4.銅合金:4%(40000ppm)
Heavy metals (重金屬)	Cadmium (Cadmium Compounds)	鍋及其 化合物	Cd	80ppm	
	Mercury (Mercury Compounds)	汞及其 化合物	Hg	800ppm	
	Hexavalent Chromium	六價鉻 及其化 合物	Cr^{+6}	800ppm	
Bromided organic	PBBs	聚溴聯 苯	C12H12- XBrXO (X=1~10)	800ppm	
compounds (含 溴有機化合物)	PBDEs PBDOs	聚溴二 苯醚	C12H12- XBrXO (X=1~10)	800ppm	
Heavy metals (重金屬) (applicable to packaging(包裝 材適用))	Pb+Cd+Hg + Cr ⁺⁶ (applicable to packaging)	鉛+鎘+ 汞+六價 鉻(包裝 材適用)	Pb+Cd+H g+ <i>Cr</i> +6 (包裝材 適用)	80ppm(Cd <5 ppm)	含棧板、膠膜、膠帶、膠袋、 緩衝材、發泡材、紙箱、 label、Tray、束帶、乾燥包、 真空袋、溼度指示卡等及上述 材料印刷所用油墨。

Advance Multimedia Internet Technology Inc. 限用物質承諾保證書 Guarantee of Hazardous Substances

供應商名稱 (Supplier's Name): 嘉光科技股份有限公司

本公司特此保證:保證供應給<u>水洋科技股份有限公司</u>的產品滿足以下列出的有害物質限值的要求,並於製程中不使用該項物質:

We warrant that all the products supplied to Advance Multimedia Internet Technology Inc. satisfy the following threshold requirements concerning hazardous substances, and the use of these substances used in the production of

supplied products are in compliance with such threshold requirements: 永洋針對ROHS規定 SONY SS-00259限 Name of hazardous 有害物質名稱 substance 限定值 (limit for 定值 (limit for SONY RoHS) -00259) ppm (mg/kg) ppm (mg/kg) 80 Solder:75ppm Plastics/Wire Cadmium and its compounds 镉及其混合物 5ppm Solder:20ppm Plastic/Painting/W Lead and its compounds (Pb) 800 鉛及其混合物 *鋼(steel) 3500 ire 100ppm *紹(aluminum) 4000 *銅(copper) 4% Solder: 1000ppm 800 Mercury and its compounds 汞及其混合物 Chromium VI and its 800 六價鉻及其混合 compounds (Cr) 800 Polybrominated Biphenyls 多溴聯苯(PBB) (PBB) Polybromodiphenyl ether 800 多溴二苯醚 (PBDE) Packaging: 100 Packaging: 80 鑷+鉛+汞+六價 Cd+ Pb+ Hg+ Cr 所有乾電池及蓄電池之產品應符合以下規定: Mercury and its 5PPM 5PPM 汞及其混合物 1 PPM(供中國用 25mg/cell compounds (Hg) 的錳電池及碱錳電



Cadmium and its compounds

Lead and its compounds (Pb)

额及其混合物

鉛及其混合物

Entire Specimen shall be follow the destruct testing of RoHS Homogenous.

250PPM

4,000PPM





池)

4,000PPM

0

Advance Multimedia Internet Technology Inc.

※本公司特此保證,自<u>2006</u>年<u>01</u>月<u>01</u>日起,提供給<u>永洋科技股份有限公司</u>產品或零件中,符合RoHS或Sony SS-00259的危害物質限質要求之含量標準。

We also warrant that the products listed hereafter, which will be supplied to Advance Multimedia Internet Technology Inc. (Amit)

from 2006/01/01, satisfy RoHS and/or Sony SS-00259 requirements concerning hazardous substances.

※若本公司違反上述限值標準,因而造成貴公司的一切損失及風險,本公司將承擔一 切責任,並承擔補償貴公司因此發生的一切費用。

We shall pay to Amit all damages and costs including, but not limited to, reasonable attorneys' fees, damage awards, payments to settle claims, and the cost of Amit internal resources handling such matters if the parts delivered to Amit failed to meet the abovementioned requirements.

※若本公司設計變更涉及材質改變或製程改變或製造場所改變,必須重新提出「環境管理物質」檢測報告供 貴公司存查,若未提出相關之檢測報告,而經貴公司或貴公司之客戶發現者,除需負擔貴公司發生之一切費用(包含但不限於檢測費用、損失)外,另需給付懲罰性違約金新台幣100,000元。

We shall propose again that the examining report supports Amit to be keep for reference on the "Environmental management material", if the product design change involve material or process or manufacture place if not provide any testing report, but discovered by AMIT or AMIT's customers, shall be share the full expenses cause by the said issue (including but no limited of testing expenselose), but shall addition pay in the amount of NTD 100,000 for penalty.

※ 本公司對限用物質(RoHS)或(SS-00259),承諾之料件內/外箱標示。

The following label (please check the appropriate box) will be used for the of shipping RoHS and/or Sony SS-00259 compliant parts on their internal and external packaging:

□按永洋科技股份	分有限公司之規定標示如下	
Amit's label:		



26mmx26mm 綠底白字

□標示不同於永洋科技股份有限公司,說明如下:

Our own label:

※本保證書請蓋公司大小章及騎縫章後正本寄回永洋科技股份有限公司。 Please sign and return this Guarantee Form back to Amit.

公司名稱(Company Name): 嘉光科技股份有限公司

回覆日期(Date): 2007/06/26

負責人簽名(Authorized Signature):

公司章(Supplier's Company Stamp):









電子類物料承認書 CHECK LIST v3.0 版

※ 第一頁為承認書(APPROVAL SHEET)封面,必須註明以下資訊,包括:
■ 1、永洋料號(AMIT P/N)
■2、供應商料號與供應商型號(Part NO, Internal code)
■3、承認書版次,依承認書初次開始編製(如 A、B、C or 1、2、3),勿以料號版次編製
■4、產品名稱(如彩盒、說明書、外箱…等)
※ 第二頁必需爲承認書的目錄,而且必須符合下列的格式:
※ 目錄(Specification Index)
■.1、規格(specification)
■ 2、圖面(mechanical drawing)(<u>須包含本體表面印刷文字(廠牌、型號、date code)說明</u>)
■ 3、性能檢測報告(Performance Test Report)
■ a、可靠度測試報告(Reliability Test Report)(shielding case、外露 connector 鹽霧測試
報告、電池必須提供)
■ b、各項性能測試報告(performance report)(天線、電池)
■ 4、最小之內包裝方式(Packing information)(卷、管、盤狀物料,若 data sheet 已說明則不
需另外提供)
□ 5、製程溫度資訊(Thermal Profile),爲獨立一份檔案(針對永洋主、被動元件一定需提供)
(項目 6 爲針對 PCB 供應商須提供,)
□ a、文字、孔位、PAD 點及線路等底片
□ b、切片報告(microdection report)及切片樣本
□ c、阻抗報告(impedance report)及阻抗條
□ d、成品出貨檢驗報告
□ e、疊構方式切面圖及連板成型圖
□ f、PCB 耐溫耐熱測試報告
□ g、材質證明及 UL 認證
☐ h、GERBER DRAWING
□ i、製作規範
■ 7、永洋 RoHS 調査表(請另外填寫"永洋 RoHS 調査表範本_for 零件供應商(Excel 檔)"
並按照內容範例及說明指示提供所需要的資料,並將第三公證單位測試報告檔案
附加至 Excel 檔中。)
請注意
※ 限用物質承諾保證書須在送樣承認前經 AMIT 稽核審查合格,方可進行承認流程。
※ 送樣承認時須同時檢附 AMIT RoHS 調查表,Excel File。
※ 請務必依 Check List 所條列之項目,於承認書送出時確認資料是否完整正確 ※

AMIT 申請人員確認: (永洋申請人姓名); 供應商確認: (尹廣汶)



Product Hazardous Substance Report

Model Name:

Part Number: Date: 2013/2/28

RoHS Directive 2011/65/EC & PFOS Directive 200	6/122/EC
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Item 項目	Part Number 料號	Descriptio n 品名	Com pon ent	SUPPLIER PN 原廠/製造	Weigh t (mg)		Sub-parts Homogeneo us Material 分離之均匀 材質名稱	顏色 (塑膠、 油墨及 漆料必 塡) The	與否/鍍層 材質說明 If the plating layer exist or not?(Y/N) /If yes,	均勻材	Effective date 報告生效 日	1,000	100	1,000	00 1,000 1,000 1,000			Control Substance; mg/kg Concerned			ng/kg		
			Sup plier s 廠商名稱	商型號		万離材 質 項目				質 單重 (mg)		Pb 鉛	Cd 鎘	Hg 汞	Cr+ 6 六價鉻	РВВ	PBDE	HBCCD	DEHP	ВВР	DBP	PFOA	
1	1 11320Y11141A1	CHIP Antenna AT3216- T2R4PAA	璟德 電子	AT3216- T2R4PAAT/ LF	T2R4PAAT/ 1	18.48	1	Ceramic	NA	N	16.22	2012/3/8 2012/5/18	N.D	N.D	N.D	N.D	N.D	N.D	-	-	-	1	N.D
		TLF				2	Termination Plating	NA	Y(Ni / Sn)	2.26	2012/5/18 2012/5/18	N.D	N.D	N.D	N.D	N.D	N.D	-	-	-	-	N.D	

						REACH Reg	ulation (EC) No	1907/2006	ŀ				
=ppm PFOS	Analysis report No. 實驗室分析報 告號碼	Laboratory Test Report (Hyperlink) 第三公證單位 化學分析報告	Material Declaration / Exception Declaration 物質宣告 書或排外 宣告證明 (Hyperlink)	元素/化合物	分元素表 元素/化 合物 比重 (%)	Contanted Substance of SVHC	Candidate List Update Date by			erned Br 溴	(Hyperlink)	Material Declaration (Hyperlink) 物質宣告書	備註 Remark
	CE/2012/30808	CE_2012_30808.pd		A12O3	57.0%	No	12/19/2012						
				SiO2	28.2%	No	12/19/2012						
N.D				CaO	8.1%	No	12/19/2012		N.D	ND			
N.D	CE/2012/52120	sor		TiO2	1.8%	No	12/19/2012		N.D	N.D			
		CE_2012_52120		MgO	1.0%	No	12/19/2012				205		
				Ag	4.0%	No	12/19/2012				CE_2012_52120		
		968		Ag	65.1%	No	12/19/2012						
ND	CE/2012/52122	CE_2012_52122		Ni	11.6%	No	12/19/2012		N.D	N.D			
N.D	CE/2012/52120			Sn	23.2%	No	12/19/2012		N.D	N.D			